TIL186-1, TIL186-2, TIL186-3, TIL186-4 AC-INPUT OPTOCOUPLERS

SOOS011A D2981, DECEMBER 1986-REVISED JUNE 1989

- A-C Signal Input
- Gallium Arsenide Dual-Diode Infrared Sources Coupled to a Silicon NPN Photo-Transistor
- Plastic Dual-In-Line Package
- UL-Recognized File # E65085

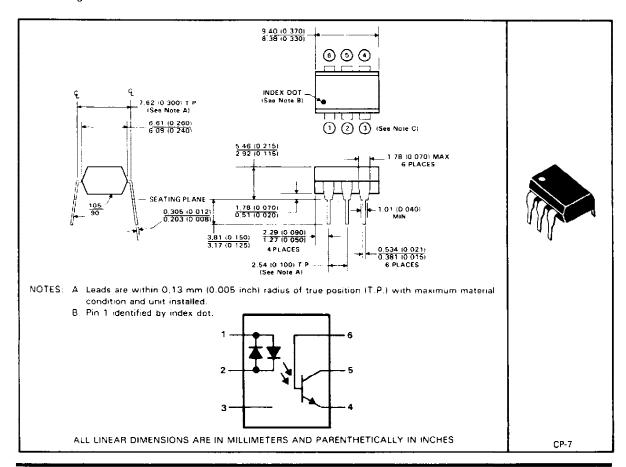
- Choice of Four Current Transfer Ratios
- High-Voltage Electrical Isolation
 3.535 kV Peak (2.5 kV rms)
- High-Speed Switching . . . t_f = 4 μs Typ

description

The TIL186 optocoupler is designed for use in ac input signal applications that require high-voltage isolation between input and output. Users can select from four different current gains (TIL186-1 through TIL186-4). These optocouplers consist of two GaAs light-emitting input diodes connected in a reverse-parallel configuration for ac input applications and a silicon npn output phototransistor.

mechanical data

The package is mounted on a 6-pin lead frame encapsulated within an electrically nonconductive plastic compound. The case will withstand soldering temperature with no deformation. Device performance characteristics will remain stable when operated in high-humidity conditions. Unit weight is approximately 0.52 grams.



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TIL186-1, TIL186-2, TIL186-3, TIL186-4 AC-INPUT OPTOCOUPLERS

absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)
Input-to-output voltage
Collector-base voltage
Collector-emitter voltage (see Note 1)
Emitter-collector voltage
Emitter-base voltage
(see Note 2)
Continuous power dissipation at (or below) 25°C free-air temperature:
Infrared-emitting diode (see Note 3)
Phototransistor (see Note 3)
Infrared-emitting diode plus phototransistor (see Note 4)
Storage temperature range
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds
NOTES: 1. This value applies when the base-emitter diode is open circuited.
Derate linearly to 100°C free-air temperature at the rate of 1.33 mA/°C.
 Derate linearly to 100°C free-air temperature at the rate of 2 mW/°C.
4. Derate linearly to 100°C free-air temperature at the rate of 3.33 mW/°C.

electrical characteristics at 25°C free-air temperature (unless otherwise noted)

PARAMETER			TEST CONDITIONS			MIN	TYP	MAX	UNIT
V(BR)CBO Collector-base breakdown voltage			I _C = 10 μA,	I _E = 0,	(F = 0	100			V
V(BR)CEO Collector-emitter breakdown voltage		l _C = 1 mA,	I _B = 0,	IF = 0	55			٧	
V(BR)EBO Emitter-base breakdown voltage		l _E = 10 μA,	IC = 0,	IF = 0	7			>	
V(BR)ECO Emitter-collector breakdown voltage			le = 100 μA,	$l_B = 0$,	IF = 0	7		-	٧
		Phototransistor operation	V _{CE} = 10 V, 1 _B = 0	lε = 2 mA,	TIL186-1	0.1			
	On-state collector current				TIL186-2	0.2			
					TIL186-3	0.5			
			-,-		TIL186-4	1			
[†] Cioni [†]					TIL186-1	1			mA
			V _{CE} = 10 V,	le = 10 mA,	TIL186-2	2			
					TIL186-3	5		,	
					TIL186-4	10			
		Photodiode operation	V _{CB} = 10 V.	lp = 10 mA.	ie = 0	5	12	,	μA
(C(off)	Off-state collector current		$V_{CE} = 50 \text{ V}$	fr = 20 mA,	ig = 0		2	200	nΑ
h _{FE}	Transistor static forward current transfer ratio		V _{CE} = 5 V,	IC = 10 mA,	IF = 0	100	550		
V _F ↑	Input diode static forward voltage		I _F = 10 mA			1	1.16	1.5	V
VCE(sat) [†]	Collector-emitter saturation voltage		† _C = 1 mA,	l _F = 10 mA.	iB = 0		0.14	0.4	V
rio	Input-to-output internal resistance		V _{in out} = ±500 V,	See Note 5		1011			Ω
C _{io}	Input-to-output capacitance		$V_{in\cdot out} = 0.$	f - 1 MHz.	See Note 5		1	2	pF
Cion)1 Cion)2	On-state collector current symmetry ratio (see Note 6)		V _{CE} - 10 V,	IF = 10 mA,	IE = 0	1		3	

[†]These parameters apply for either direction of the input current.

switching characteristics at 25 °C free-air temperature

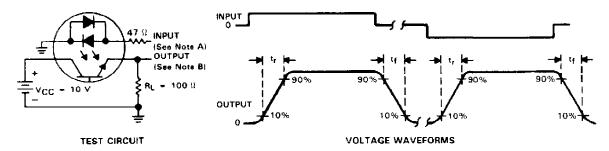
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
tr	Rise time			4	10	μS
16	Fall time	V_{CC} = 10 V, $I_{C(on)}$ = 2 mA, R_L = 100 Ω , See Figure 1		4	10	μS

NOTES: 5. These parameters are measured between both input diode leads shorted together and all the phototransistor leads shorted together.

^{6.} The higher of the two $I_{C(on)}$ values generated by the two diodes is taken as $I_{C(on)}1$

PARAMETER MEASUREMENT INFORMATION

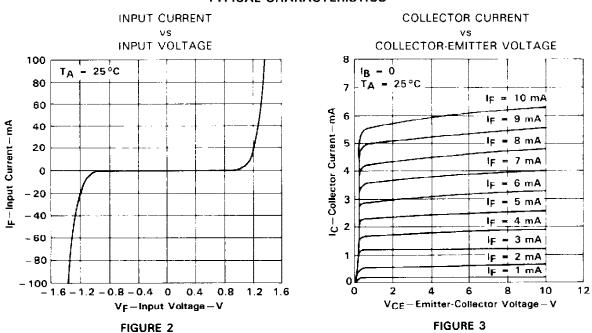
Adjust amplitude of input pulse is for IC(on) = 2 mA



NOTES: A. The input waveform is supplied by a generator with the following characteristics: $Z_0 = 50 \,\Omega$, $t_r = \pm 15 \,\text{ns}$, duty cycle = 1%. B. The output waveform is monitored on an oscilloscope with the following characteristics: $t_r \le 12 \,\text{ns}$, $R_l \ge 1 \,M\Omega$, $C_l \le 20 \,\text{pF}$.

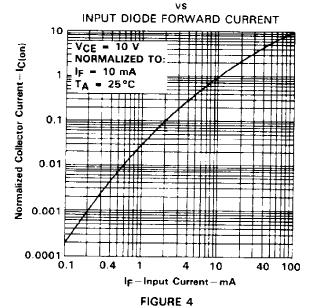
FIGURE 1. SWITCHING TIMES

TYPICAL CHARACTERISTICS

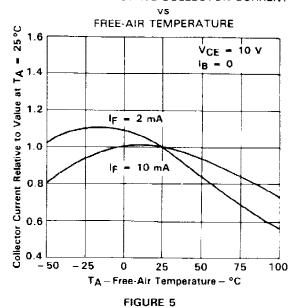


TYPICAL CHARACTERISTICS

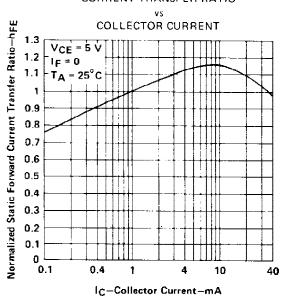
NORMALIZED ON-STATE COLLECTOR CURRENT



RELATIVE ON-STATE COLLECTOR CURRENT



NORMALIZED TRANSISTOR STATIC FORWARD CURRENT TRANSFER RATIO



NORMALIZED TRANSISTOR STATIC FORWARD CURRENT TRANSFER RATIO

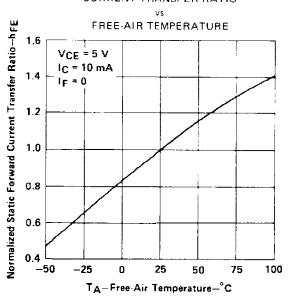


FIGURE 6 FIGURE 7

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PACKAGE OPTION ADDENDUM

8-Apr-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TIL186-1	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI
TIL186-2	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI
TIL186-3	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI
TIL186-4	OBSOLETE	PDIP	N	6	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

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PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

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TBD: The Pb-Free/Green conversion plan has not been defined.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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